



Material Content Data Sheet



Sales Product Name		BTS5008-1EKB		Issued		29. August 2013		
MA#		MA001109718						
Package		PG-DSO-14-47		Weight*		151.05 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.820	3.19	3.19	31912	31912
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		114	
	non noble metal	zinc	7440-66-6	0.069	0.05		458	
	non noble metal	iron	7439-89-6	1.383	0.92		9159	
wire	non noble metal	copper	7440-50-8	56.175	37.19	38.17	371902	381633
	non noble metal	copper	7440-50-8	0.787	0.52	0.52	5210	5210
	organic material	carbon black	1333-86-4	0.165	0.11		1093	
encapsulation	plastics	epoxy resin	-	7.593	5.03		50269	
	inorganic material	silicondioxide	60676-86-0	74.775	49.50	54.64	495041	546403
leadfinish	non noble metal	tin	7440-31-5	2.472	1.64	1.64	16364	16364
plating	noble metal	silver	7440-22-4	1.470	0.97	0.97	9734	9734
glue	plastics	epoxy resin	-	0.231	0.15		1530	
	noble metal	silver	7440-22-4	1.090	0.72	0.87	7214	8744
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com